

## N-Channel Super Junction Power MOSFET III

### General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

### Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

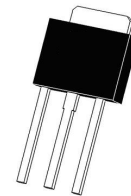
$V_{DS}$	650	V
$R_{DS(ON)TYP.}$	1600	m $\Omega$
$I_D$	3	A



Schematic diagram

### Package Marking And Ordering Information

Device	Device Package	Marking
VCRR65T1K9I	TO-251	VCRR65T1K9I
VCRR65T1K9K	TO-252	VCRR65T1K9K



TO-251



TO-252

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	650	V
Gate-Source Voltage ( $V_{DS}=0V$ ), AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	3	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	1.85	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	12	A
Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	22	W
Derate above $25^\circ\text{C}$		0.176	W/ $^\circ\text{C}$
Single pulse avalanche energy (Note2)	$E_{AS}$	16	mJ
Avalanche current (Note 1)	$I_{AR}$	0.4	A
Repetitive Avalanche energy, $t_{AR}$ limited by $T_{jmax}$ (Note 1)	$E_{AR}$	0.1	mJ

Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leq 480V$ ,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+150	°C

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	5.68	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	°C /W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

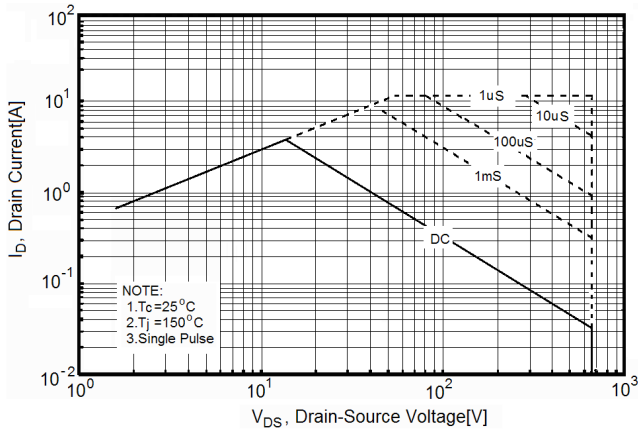
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On/off states</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current( $T_C=25^\circ C$ )	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			1	$\mu A$
Zero Gate Voltage Drain Current( $T_C=125^\circ C$ )	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			50	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3		4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=1.5A$		1600	1900	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V,$ $F=1.0MHz$		130		pF
Output Capacitance	$C_{oss}$			10		pF
Reverse Transfer Capacitance	$C_{rss}$			0.6		pF
Total Gate Charge	$Q_g$	$V_{DS}=480V, I_D=3A,$ $V_{GS}=10V$		9		nC
Gate-Source Charge	$Q_{gs}$			2.5		nC
Gate-Drain Charge	$Q_{gd}$			4		nC
<b>Switching times</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=380V, I_D=1.5A,$ $R_G=4.7\Omega, V_{GS}=10V$		10		nS
Turn-on Rise Time	$t_r$			9		nS
Turn-Off Delay Time	$t_{d(off)}$			56		nS
Turn-Off Fall Time	$t_f$			11		nS
<b>Source- Drain Diode Characteristics</b>						
Source-drain current(Body Diode)	$I_{SD}$	$T_C=25^\circ C$			4	A
Pulsed Source-drain current(Body Diode)	$I_{SDM}$				16	A
Forward On Voltage	$V_{SD}$	$T_J=25^\circ C, I_{SD}=3A, V_{GS}=0V$		0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, I_F=1.5A, di/dt=100A/\mu s$		190		nS
Reverse Recovery Charge	$Q_{rr}$			0.5		$\mu C$
Peak reverse recovery current	$I_{rrm}$			5		A

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

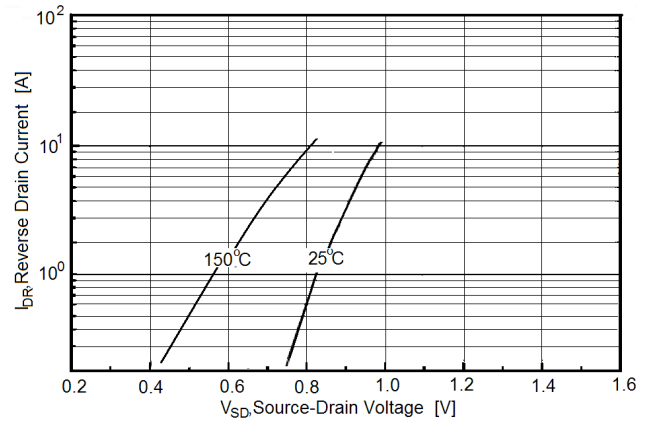
2.  $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)**

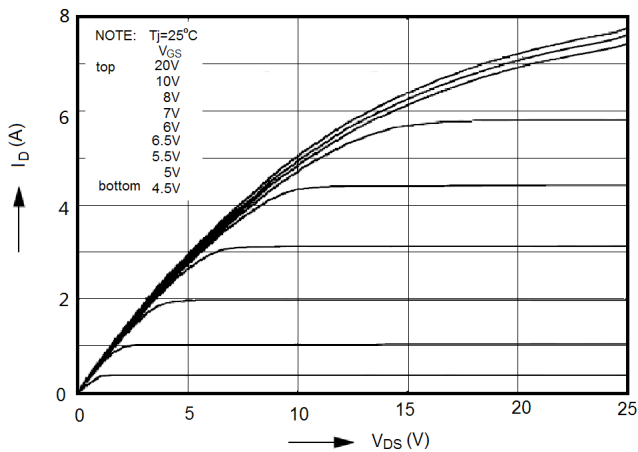
**Figure1. Safe operating area**



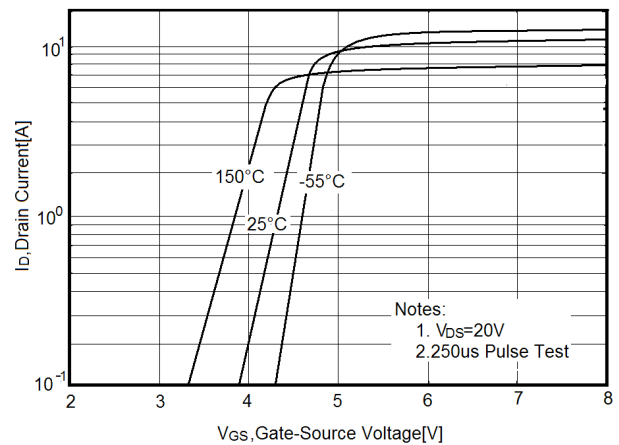
**Figure2. Source-Drain Diode Forward Voltage**



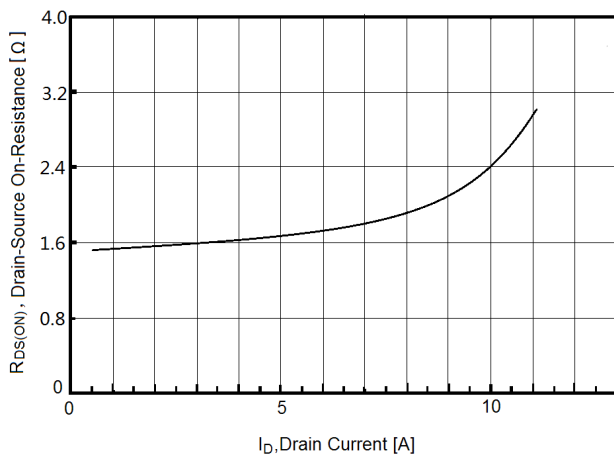
**Figure3. Output characteristics**



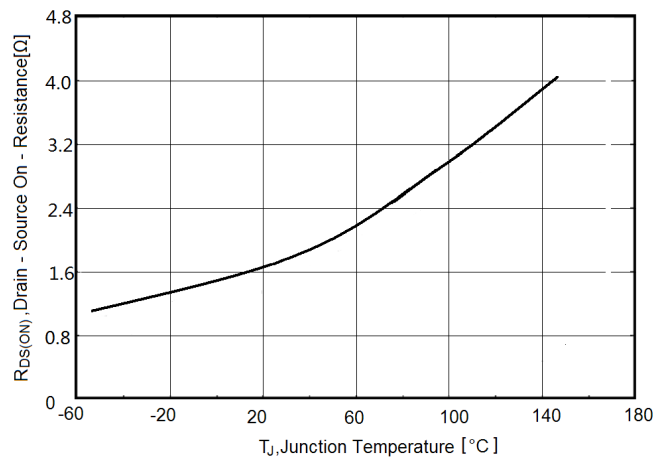
**Figure4. Transfer characteristics**



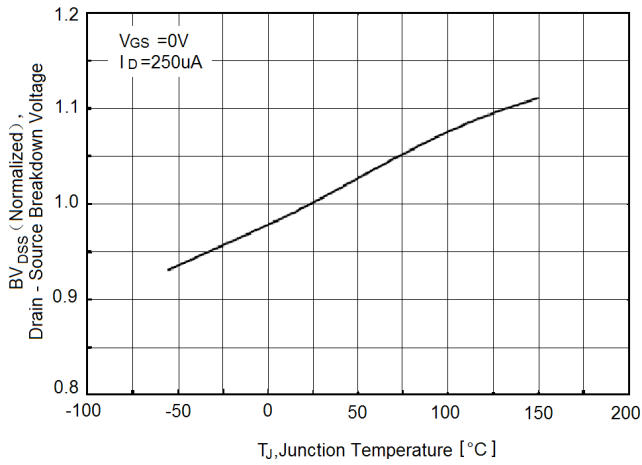
**Figure5. Static drain-source on resistance**



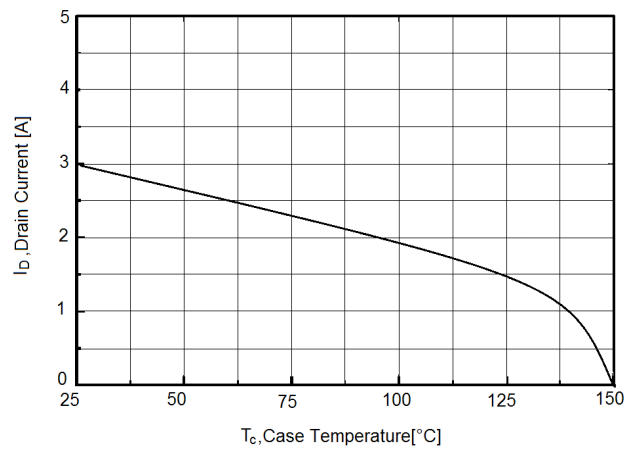
**Figure6.  $R_{DS(ON)}$  vs Junction Temperature**



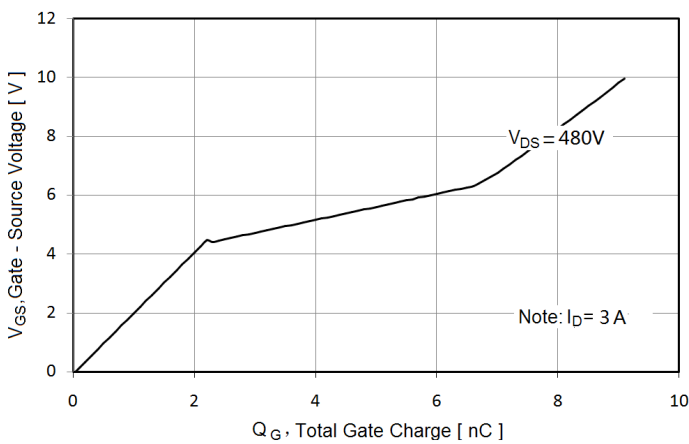
**Figure7.  $BV_{DSS}$  vs Junction Temperature**



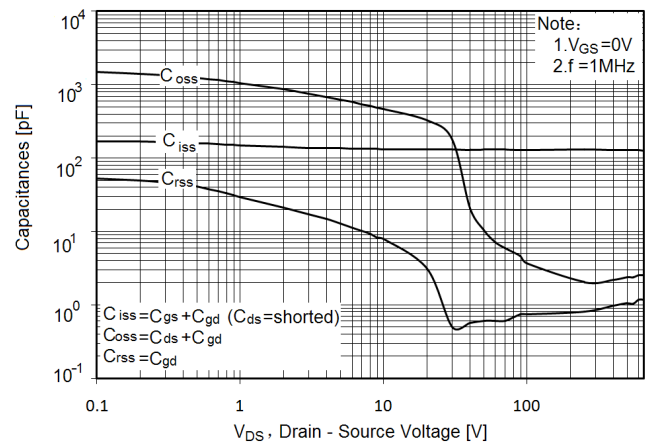
**Figure8. Maximum  $I_D$  vs Junction Temperature**



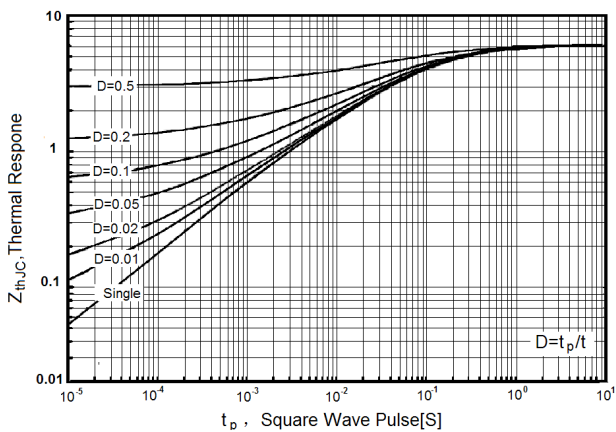
**Figure9. Gate charge waveforms**



**Figure10. Capacitance**

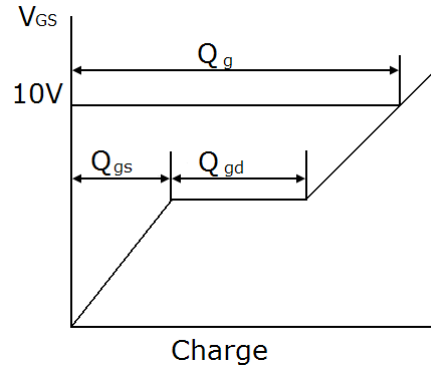
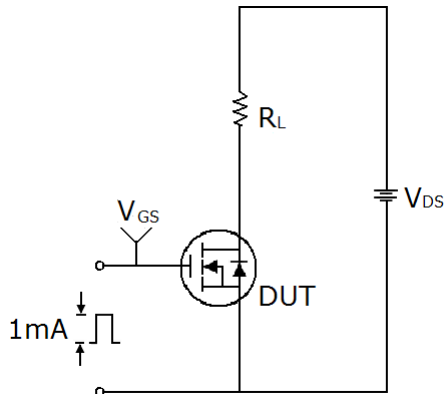


**Figure11. Transient Thermal Impedance**

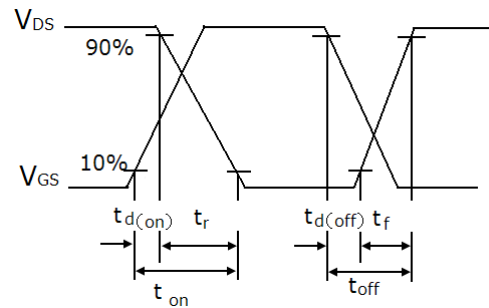
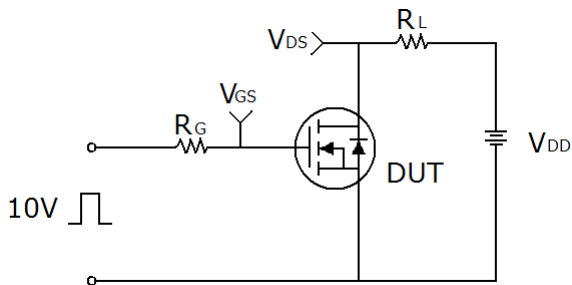


## Test circuit

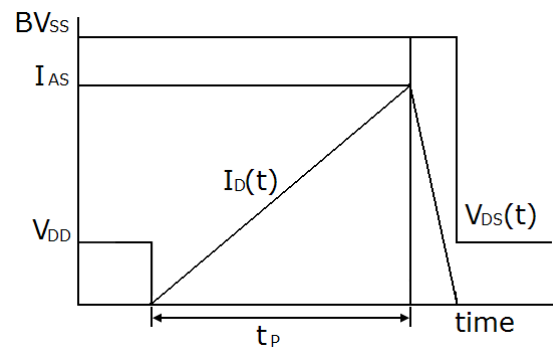
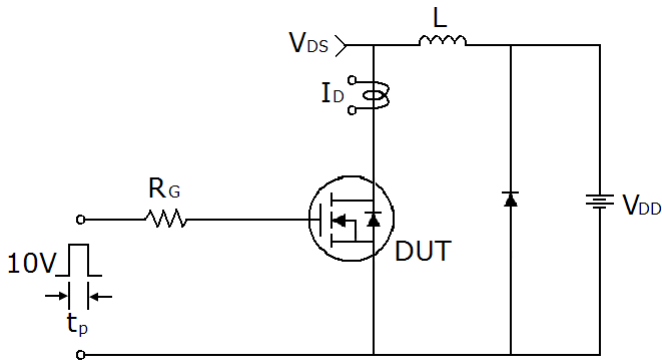
### 1) Gate charge test circuit & Waveform



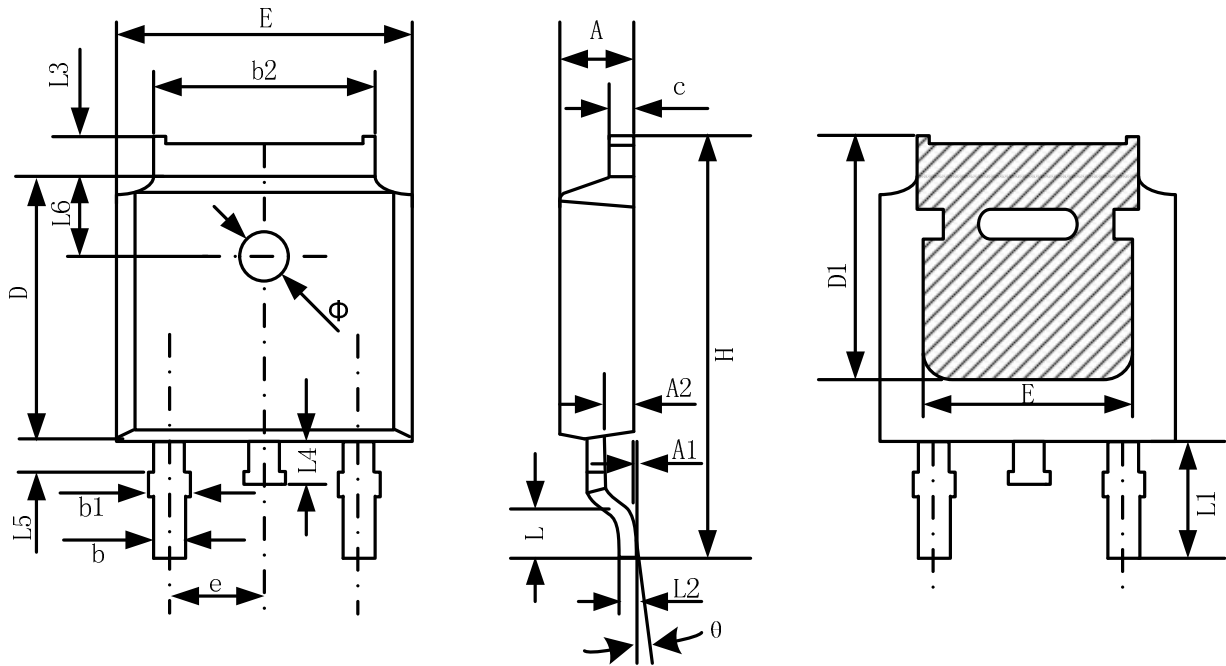
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms

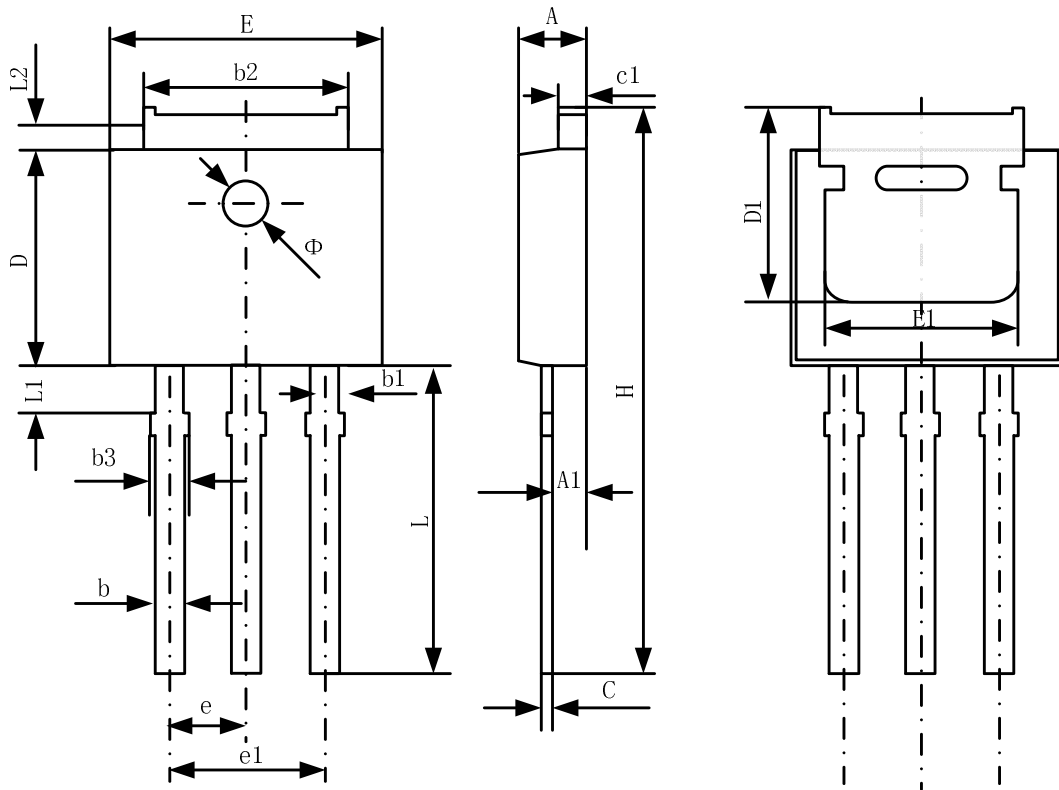


## TO-252-2 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
c	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	--	0.207	--
E	6.50	6.70	0.256	0.264
E1	4.70	--	0.185	--
e	2.19	2.39	0.086	0.094
H	9.80	10.40	0.386	0.409
L	1.40	1.70	0.055	0.067
L1	2.90 REF		0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80 REF		0.071 REF	
Φ	1.20	1.40	0.047	0.055
θ	0°	8°	0°	8°

## TO-251 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.35	0.087	0.093
A1	0.90	1.10	0.035	0.043
b	0.56	0.69	0.022	0.027
b1	0.77	0.90	0.030	0.035
b2	5.23	5.43	0.206	0.214
b3		1.05	0.000	0.041
C	0.46	0.59	0.018	0.023
c1	0.46	0.59	0.018	0.023
D	6.00	6.20	0.236	0.244
D1	5.20		0.205	
E	6.50	6.70	0.256	0.264
E1	4.60	5.00	0.181	
e	2.24	2.34	0.088	0.092
e1	4.47	4.67	0.176	0.184
H	16.18	16.78	0.637	0.661
L	9.00	9.60	0.354	0.378
L1	0.95	1.35	0.037	0.053
L2	0.90	1.25	0.035	0.049

## ATTENTION

QIAOXIN assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all QIAOXIN products described or contained herein. QIAOXIN products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. QIAOXIN reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.